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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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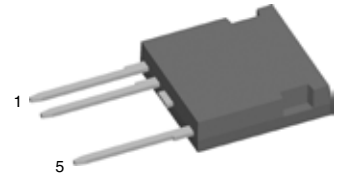
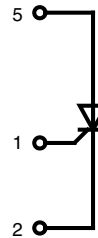


# High Voltage Phase Control Thyristor

## in High Voltage ISOPLUS i4-PAC™

$$\begin{aligned}
 V_{\text{DRM}} = V_{\text{RRM}} &= 2200 \text{ V} \\
 I_{\text{T(AV)}} &= 18 \text{ A} \\
 I_{\text{TSM}} &= 200 \text{ A}
 \end{aligned}$$

$V_{\text{RSM}}$ $V_{\text{DSM}}$ V	$V_{\text{RRM}}$ $V_{\text{DRM}}$ V	Type
2300	2200	CS 20-22moF1



### Thyristor

Symbol	Conditions	Maximum Ratings
$V_{\text{DRM}} / \text{RRM}$		2200 V
$I_{\text{T(AV)}}$	sine 180°; $T_{\text{C}} = 90^{\circ}\text{C}$	18 A
$I_{\text{T(AV)}}$	square; $d = 1/3$ ; $T_{\text{C}} = 90^{\circ}\text{C}$	16 A
$I_{\text{TSM}}$	sine 180°; $t = 10 \text{ ms}$ ; $V_{\text{R}} = 0 \text{ V}$ ; $T_{\text{VJ}} = 25^{\circ}\text{C}$	200 A
$(di/dt)_{\text{cr}}$	$T_{\text{VJ}} = T_{\text{VJM}}$ repetitive, $I_{\text{T}} = 40 \text{ A}$ $f = 50 \text{ Hz}$ ; $t_{\text{p}} = 200 \mu\text{s}$	100 A/ $\mu\text{s}$
	$V_{\text{D}} = 2/3 V_{\text{DRM}}$ $I_{\text{G}} = 0.45 \text{ A}$ non repetitive, $I_{\text{T}} = 20 \text{ A}$ $di_{\text{G}}/dt = 0.45 \text{ A}/\mu\text{s}$	250 A/ $\mu\text{s}$
$(dv/dt)_{\text{cr}}$	$T_{\text{VJ}} = T_{\text{VJM}}$ ; $V_{\text{D}} = 2/3 V_{\text{DRM}}$ $R_{\text{GK}} = \infty$ ; method 1 (linear voltage rise)	2500 V/ $\mu\text{s}$

### Features

- high voltage thyristor
  - for line frequency
  - chip technology for long term stability
- ISOPLUS i4-PAC™
  - high voltage package
  - isolated back surface
  - enlarged creepage towards heatsink
  - enlarged creepage between high voltage pins
  - application friendly pinout
  - high reliability
  - industry standard outline

### Applications

- controlled rectifiers
  - power supplies
  - drives
- AC switches
- capacitor discharge control
  - flash tubes
  - X-ray and laser generators

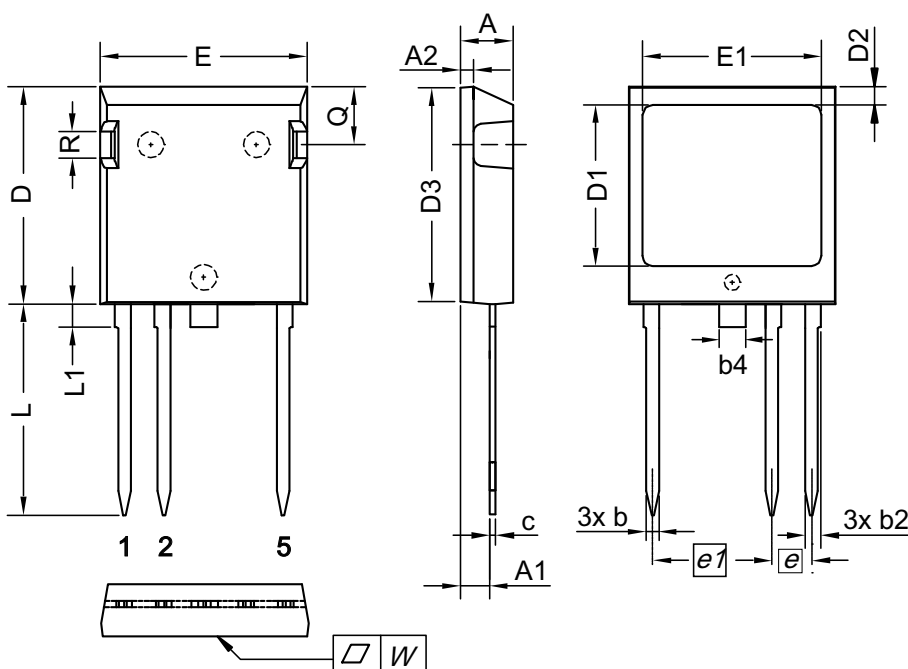
Symbol	Conditions	Characteristic Values ( $T_{\text{VJ}} = 25^{\circ}\text{C}$ , unless otherwise specified)		
		typ.	max.	
$V_{\text{T}}$	$I_{\text{T}} = 20 \text{ A}$ ;	$T_{\text{VJ}} = 25^{\circ}\text{C}$	1.3	1.5 V
		$T_{\text{VJ}} = 125^{\circ}\text{C}$	1.3	
$V_{\text{GT}}$	$V_{\text{D}} = 6 \text{ V}$			2.3 V
$I_{\text{GT}}$				250 mA
$V_{\text{GD}}$	$V_{\text{D}} = 2/3 V_{\text{DRM}}$ ;	$T_{\text{VJ}} = T_{\text{VJM}}$		0.2 V
$I_{\text{GD}}$				5 mA
$I_{\text{L}}$	$t_{\text{p}} = 10 \mu\text{s}$ ; $V_{\text{D}} = 6 \text{ V}$ $I_{\text{G}} = 0.45 \text{ A}$ ; $di_{\text{G}}/dt = 0.45 \text{ A}/\mu\text{s}$			500 mA
$I_{\text{H}}$	$V_{\text{D}} = 6 \text{ V}$ ; $R_{\text{GK}} = \infty$			150 mA
$t_{\text{gd}}$	$V_{\text{D}} = 1/2 V_{\text{DRM}}$ $I_{\text{G}} = 0.45 \text{ A}$ ; $di_{\text{G}}/dt = 0.45 \text{ A}/\mu\text{s}$			2 $\mu\text{s}$
$I_{\text{R}}, I_{\text{D}}$	$V_{\text{R}} = V_{\text{RRM}}$ ; $V_{\text{D}} = V_{\text{DRM}}$ ;	$T_{\text{VJ}} = 25^{\circ}\text{C}$		50 $\mu\text{A}$
		$T_{\text{VJ}} = 125^{\circ}\text{C}$	2	mA
$R_{\text{thJC}}$	DC current			0.92 K/W

Component			
Symbol	Conditions	Maximum Ratings	
$T_{VJ}$		-40 ... +125	°C
$T_{stg}$		-55 ... +125	°C
$V_{ISOL}$	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$	2500	V~
$F_C$	mounting force with clip	20...120	N

Symbol	Conditions	Characteristic Values	
		min.	typ.
$d_S, d_A$	A pin - K pin	7	mm
	pin - backside metal	5.5	mm
$R_{thCH}$	with heatsink compound		0.15 K/W
<b>Weight</b>			5.5 g

Dimensions in mm (1 mm = 0.0394")



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.83	5.21	0.190	0.205
A1	2.59	3.00	0.102	0.118
A2	1.17	2.16	0.046	0.085
b	1.14	1.40	0.045	0.055
b2	1.47	1.73	0.058	0.068
b4	2.54	2.79	0.100	0.110
c	0.51	0.74	0.020	0.029
D	20.80	21.34	0.819	0.840
D1	14.99	15.75	0.590	0.620
D2	1.65	2.03	0.065	0.080
D3	20.30	20.70	0.799	0.815
E	19.56	20.29	0.770	0.799
E1	16.76	17.53	0.660	0.690
e	3.81 BSC		0.150 BSC	
e1	11.43 BSC		0.450 BSC	
L	19.81	21.34	0.780	0.840
L1	2.11	2.59	0.083	0.102
Q	5.33	6.20	0.210	0.244
R	2.54	4.57	0.100	0.180
W	-	0.10	-	0.004

Die konvexe Form des Substrates ist typ. < 0.05 mm über der Kunststoffoberfläche der Bauteilunterseite  
 The convexbow of substrate is typ. < 0.05 mm over plastic surface level of device bottom side